



**DPO2039** 

### 4-CH OVER-VOLTAGE PROTECTION FOR CC/DIFF PINS ON USB TYPE-C

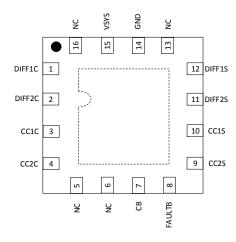
## **Description**

The DPO2039 provides 4 channels of over-voltage protection over the CC1/2 & DIFF1/2 pins which are connected to the USB Type-C connector. The 4 channels are divided into two pairs, one pair of channels protect the CC1 and CC2 pins from being shorted to the V<sub>BUS</sub>, one pair of channels protect the DIFF1 and DIFF2 pins from being shorted to the V<sub>BUS</sub>. Whenever the voltage threshold set for any of the two pairs of channels is reached, the exception condition becomes valid and the low-active flag FAULTB is subsequently asserted.

This device is designed to draw its operating voltage primarily from the system power, V<sub>SYS</sub>, which is either the always-ON 3.3/5V existed within the system or the 1-cell battery inside the mobile system. Under the circumstance when the battery inside a mobile system is fully depleted, DPO2039 can obtain power from the external peripheral system connected to the USB Type-C connector. The DPO2039 is housed in the low-profile and space-saving U-QFN3030-16 (Type B) package which is manufactured with environmental-friendly material.

## **Pin Assignments**

## (Top View)



U-QFN3030-16 (Type B)

## **Features**

- Operating Voltage Range: 2.7V to 5.5V
- 4-Channel Over-Voltage Protection with Auto-Recovery
- IEC 61000-4-2 ESD Protection over CCxC and DIFFxC Pins
- RDS(ON) of OVP MOSFET for CC-Pin Protection:  $300m\Omega$  Typical
- R<sub>DS(ON)</sub> of OVP MOSFET for DIFF-Pin Protection: 5Ω Typical
- C<sub>IN</sub> of OVP MOSFET for CC-Pin Protection: 50pF
- C<sub>IN</sub> of OVP MOSFET for DIFF-Pin Protection: 5pF
- Built-In Over-Temperature Protection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

## **Applications**

- Notebook/Desktop/AIO PCs, Tablets, Mobile Phones
- VR/AR Headsets
- Docking Stations, Universal & Multimedia Hubs
- FPTVs, PC Monitors
- Set-Top-Boxes, Residential Gateways, Storage Devices
- Universal AC/DC Chargers/Adapters

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



# **Typical Application Circuit**

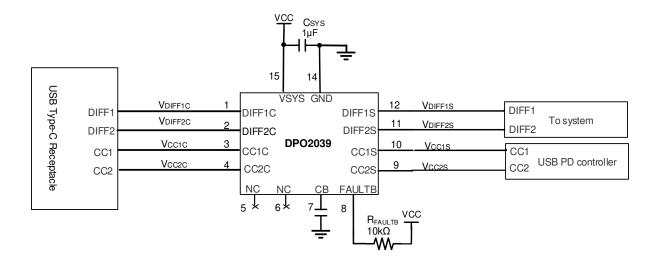


Figure 1. Typical Application Circuit

# **Pin Descriptions**

Pin Number	Pin Name	Function
1	DIFF1C	DIFF1 connector side. This shall be connected to the DIFF1 pin of the USB Type-C connector.
2	DIFF2C	DIFF2 connector side. This shall be connected to the DIFF2 pin of the USB Type-C connector.
3	CC1C	CC1 connector side. This shall be connected to the CC1 pin of the USB Type-C connector.
4	CC2C	CC2 connector side. This shall be connected to the CC2 pin of the USB Type-C connector.
7	СВ	Pin for ESD support capacitor. Place a 0.1µF capacitor on this pin to ground.
8	FAULTB	Fault status. This is an active-low open-drain output.
9	CC2S	CC2 system side. This shall be connected to the CC2 pin of the component to be protected.
10	CC1S	CC1 system side. This shall be connected to the CC1 pin of the component to be protected.
11	DIFF2S	DIFF2 system side. This shall be connected to the DIFF2 pin of the component to be protected.
12	DIFF1S	DIFF1 system side. This shall be connected to the DIFF1 pin of the component to be protected.
5, 6, 13, 16	NC	No connection.
14	GND	Ground.
15	VSYS	Power Input. This shall be connected to the 2.7 to 5.5V power source inside the system.
	EP	Exposed pad. This shall be connected to ground.



# **Functional Block Diagram**

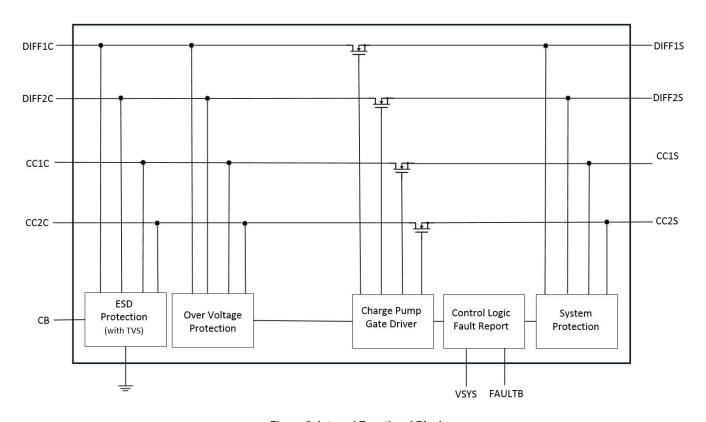


Figure 2. Internal Functional Blocks

# **Absolute Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified) (Note 4)

Symbol	Parameter	Rating	Unit
Vvsys	Voltage Range of VSYS Pin	-0.3 to 6.0	V
V <sub>FAULTB</sub>	Voltage Range of FAULTB Pin	-0.3 to 6.0	V
V <sub>CB</sub>	Voltage Range of CB Pin	-0.3 to 24	V
VDIFFXS, VCCXS	Voltage Range of DIFF1S, DIFF2S, CC1S, CC2S Pins	-0.3 to 6.0	V
VDIFFxC, VCCxC	Voltage Range of DIFF1C, DIFF2C, CC1C, CC2C Pins	-0.3 to 24.0	V
TJ	Operating Junction Temperature	-40 to +150	°C
T∟	Lead Temperature	+260	°C
Tstg	Storage Temperature	-65 to +150	°C
ESD	Human Body Model (HBM), JESD22-A114	±2.0	kV
E3D	Charge Device Model (CDM), JESD22-C101	±0.5	r, V

Note:

## Package Thermal Data (@ T<sub>A</sub> = +25°C, unless otherwise specified) (Note 5)

Symbol	Parameter	Rating	Unit
PD	Power Dissipation	1.75	W
Reja	Thermal Resistance, Junction-to-Ambient	73	°C/W
Rejc	Thermal Resistance, Junction-to-Case	12.7	°C/W

Note: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with  $1" \times 1"$  copper pad layout.

These are stress ratings only. Operation outside the absolute maximum ratings can cause device failure.
 Operation at the absolute maximum rating for extended periods can reduce device reliability.



# Recommended Operating Conditions (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Unit
Vvsys	Input Supply Voltage at VSYS Pin	2.7	5.5	V
VFAULTB	Power Rail for Pull-Up on FAULTB Pin	2.7	5.5	V
V <sub>CB</sub>	Voltage across CB Pin	0	5.5	V
Vccxc, Vccxs	I/O Voltage at CC1C, CC2C, CC1S, CC2S Pins	0	5.5	V
VDIFFXC, VDIFFXS	I/O Voltage at DIFF1C, DIFF2C, DIFF1S, DIFF2S Pins	0	4.2	V
Ivccx	Output Current Flowing into CCxS and out of CCxC, with Vccxs − Vccxc ≤ 250mV	_	600	mA

# **Electrical Characteristics** (@ T<sub>A</sub> = +25°C, V<sub>VSYS</sub> = 4.2V, unless otherwise specified.)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
CC OVP Switches						•
Б	On Besistance of CO OVE FET-	V <sub>CCxC</sub> = 5.5V, T <sub>A</sub> ≤ +85°C		300	450	mΩ
R <sub>DS(ON)_CC</sub>	On Resistance of CC OVP FETs	V <sub>CCxC</sub> = 5.5V, T <sub>A</sub> ≤ +105°C	_	300	480	mΩ
Rds(onflat) cc	On Resistance Flatness of CC OVP FETs	Vccxc = 0.1 to 1.2V	_	_	5	mΩ
Con_cc	Equivalent ON Capacitance	Capacitance from CCxC or CCxS to GND when device is powered, (VCcxC / VCcxS) = 0V to 1.2V	_	50	_	pF
VTH OVP CCxC	OVP Threshold on CCxC Signal	<u> </u>	5.6	6	6.25	V
VTH OVP HYS CCXC	OVP Hysteresis on CCxC Signal	_	_	140	_	mV
BWon_cc (Note 6)	CC Line ON Bandwidth Single Ended (-3dB)	Measured from CCxC to CCxS, $50\Omega$ system, $V_{CM} = 0.1V$ to $1.2V$	_	200	_	MHz
Vsht_ccxc_max (Note 6)	Short-to-VBUS Tolerance on the CCxC Pins	Hot-plug CCxC with a 1 meter USB Type-C cable, place a 30Ω load on CCxS	_	_	24	٧
VsHT_CCxs_CL (Note 6)	Short-to-VBUS Clamping Voltage on the CCxS Pins	Hot-plug CCxC with a 1 meter USB Type-C cable, place a 30Ω load on CCxS. Hot plug voltage Vccxc = 24V	_	7	_	٧
DIFF OVP Switches		, 5				
Б	On Resistance of DIFF OVP FETs	VDIFFxC = 3.6V, TA = +85°C	_	5	_	Ω
R <sub>DS(ON)_DIFF</sub>		VDIFFxC = 3.6V, TA = +105°C	_	5	_	Ω
RDS(ONFLAT) DIFF	On Resistance Flatness of DIFF OVP FETs	V <sub>DIFFxC</sub> = 0.1 to 3.6V	_	_	1	Ω
Con_diff	Equivalent ON Capacitance	Capacitance from DIFFxC or DIFFxS to GND when device is powered. V <sub>DIFFxC</sub> / V <sub>DIFFxS</sub> = 0V to 3.6V	_	5	_	pF
VTH OVP DIFFxC	OVP Threshold on DIFFxC Signals	_	4.15	4.5	4.75	V
VTH OVP HYS DIFFxC	OVP Hysteresis on DIFFxC Signals	_	_	110	_	mV
BW <sub>ON_DIFF</sub> (Note 6)	DIFF line ON Bandwidth Single Ended (-3dB)	Measured from DIFFxC to DIFFxS, 50Ω system, V <sub>CM</sub> = 0.1V to 3.6V	_	1000	_	MHz
V <sub>S</sub> HTBUS_DIFFxC_MAX (Note 6)	Short-to-VBUS Tolerance on the DIFFxC Pins	Hot-plug DIFFxC with a 1 meter USB Type-C cable, place a 40Ω in series with 150nF to GND on DIFFxS pin	_	_	24	V
VshtBus_DIFFxs_cL (Note 6)	Short-to-VBUS Clamping Voltage on the DIFFxS Pins	Hot-plug DIFFxC with a 1 meter USB Type-C cable, place a 40Ω in series with 100nF to GND on DIFFxS pin. Hot plug voltage V <sub>DIFFxC</sub> = 24V, Vvsys = 3.3V	_	7	_	V
XTALK_DIFFx (Note 6)	Crosstalk between DIFFx Lines	Measure crosstalk at f = 1MHz, from DIFF1S to DIFF2C or DIFF2 to DIFF1C. $V_{CM1} = 3.6V$ , $V_{CM2} = 0.3V$ , terminate open sides to $50\Omega$	_	-80	_	dB



# 

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Power Supply and Lea		100.00		- 714		
Vuvlo	Vvsys under Voltage Lockout	Vvsys steps up from 2V until CC or DIFF FETs turn ON	2.15	2.4	2.55	V
Vuvlo_Hsys	Vvsys UVLO Hysteresis	Vvsys steps down from 2.5V until CC or DIFF FETs turn off. Measure difference between rising and falling UVLO to calculate	_	200	_	mV
Ivsys_on	Vvsys Supply Current	<del>-</del>	_	190	_	μΑ
I <sub>LEAK_CCxC</sub>	Leakage current for CCxC when device is powered	$V_{CCxC} = 3.6V$	_	_	30	μΑ
ILEAK_DIFFxC	Leakage current for DIFFxC when device is powered	VDIFFxC = 3.6V	_	_	35	μΑ
ILEAK_CCxS	Leakage current for CCxS when device is powered	Vccx = 3.6V	_	_	30	μΑ
ILEAK_DIFFxS	Leakage current for DIFFxS when device is powered	VDIFFx = 3.6V	_	_	35	μA
ILEAK_OVP_CCxC	Leakage current into CCxC pins when	Vvsys = 0V, Vccxc = 22V, Vccxs = 0V	_	_	150	μΑ
ILEAK_OVP_CCXC	device is in OVP	Vvsys = 4.2V, Vccxc = 22V, Vccxs = 0V	_	_	150	μΑ
	Leakage current into DIFFxC pins when	Vvsys = 0V, V <sub>DIFFxC</sub> = 22V, V <sub>DIFFxS</sub> = 0V	_	_	200	μΑ
ILEAK_OVP_DIFFxC	device is in OVP	VVSYS = 4.2V, VDIFFXC = 22V, VDIFFXS = 0V	_	_	200	μΑ
l	Leakage current out of CCxS pins when device is in OVP	Vvsys = 0V, Vccxc = 22V, Vccxs = 0V	_	_	1	μΑ
ILEAK_OVP_CCxS		Vvsys = 4.2V, Vccxc = 22V, Vccxs = 0V	_	_	1	μA
	Leakage current out of DIFFxS pins when device is in OVP	Vvsys = 0V, Vdiffxc = 22V, Vdiffxs = 0V	_	_	1	μΑ
ILEAK_OVP_DIFFxS		V <sub>VSYS</sub> = 4.2V, V <sub>DIFFxC</sub> = 22V, V <sub>DIFFxS</sub> = 0V	_	_	1	μA
FAULTB Pin			•			•
VFAULTB	Active-Low Output Voltage of FAULTB Pin	I <sub>OL</sub> = 8mA	_	_	0.4	V
ILEAK_FAULB	FAULTB Leakage Current	VFAULTB = 4.2V	_	_	1	μΑ
TFAULTB ASSERTION	FAULTB Assertion Time	_	_	_	300	μs
tfaultb_deassertion	FAULTB Deassertion Time	_	_	4	_	ms
Timing Requirements			•	•	•	•
ton	Time from Crossing Rising Vvsys UVLO until CC/DIFF OVP FETs are on	_	_	_	2.5	ms
tovp_response_cc	OVP Response Time on the CC Pins, Time from OVP Asserted until OVP FETs Turnoff	_	_	100	_	ns
tovp_response_diff	OVP Response Time on the DIFF Pins, Time from OVP Asserted until OVP FETs Turnoff	_	_	100	_	ns
tovp_response_cc_1	OVP Recovery Time on the CC Pins. Once an OVP has occurred, the minimum duration until CC FETs turn back on if OVP has been removed already	_	26	32	38	ms
tovp_response_diff_1	OVP Recovery Time on the DIFF Pins. Once an OVP has occurred, the minimum duration until DIFF FETs turn back on if OVP has been removed already	_	26	32	38	ms
tovp_response_cc_2	OVP Recovery Time on the CC Pins. Time from OVP removal until CC FETs turn back on, if device has been in OVP > 40ms	_	_	1	_	ms
tovp_response_diff_2	OVP Recovery Time on the DIFF Pins. Time from OVP removal until DIFF FETs turn back on, if device has been in OVP > 40ms		_	1	_	ms
Thermal Shutdown and Hysteresis						
Tshon	Thermal Shut Down Threshold	_	l —	+150	_	°C
THSYS	Thermal Shut Down Hysteresis	_	<b> </b>	+20		°C
111010			l	120	l	_

Note: 6. Guaranteed by bench characterization.



## Performance Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

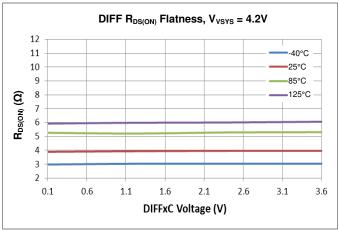


Figure 3. DIFF RDS(ON) Flatness

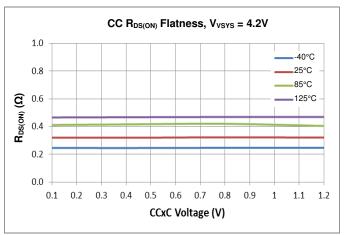


Figure 4. CC RDS(ON) Flatness

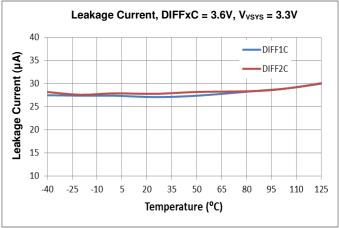


Figure 5. DIFFxC Leakage Current vs. Temperature

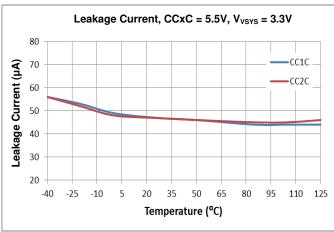


Figure 6. CCxC Leakage Current vs. Temperature

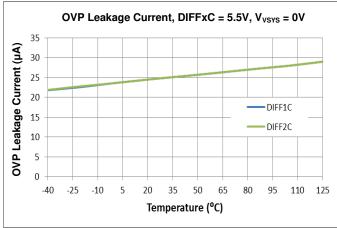


Figure 7. DIFFxC 5.5V OVP Leakage Current vs. Temperature

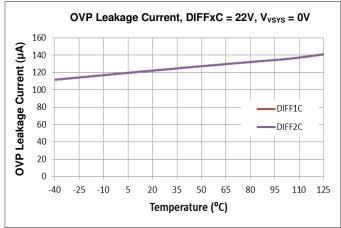


Figure 8. DIFFxC 22V OVP Leakage Current vs. Temperature



## Performance Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.) (continued)

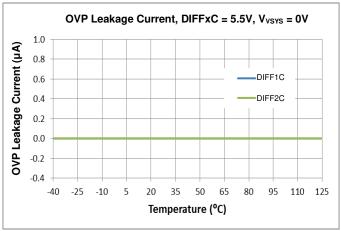


Figure 9. DIFFxC OVP Leakage Current vs. Temperature

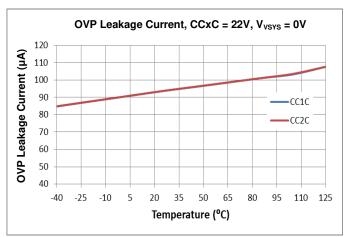


Figure 10. CCxC OVP Leakage Current vs. Temperature

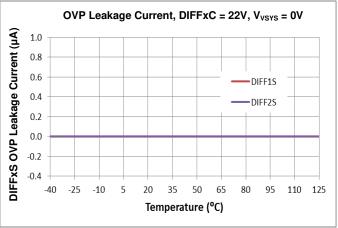


Figure 11. DIFFxS OVP Leakage Current vs Temperature

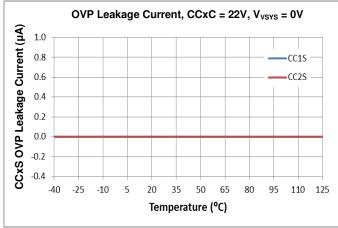


Figure 12. CCxS OVP Leakage Current vs Temperature

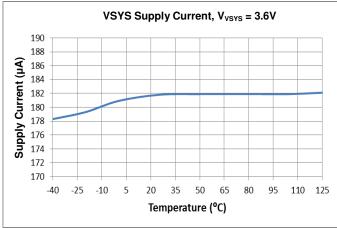


Figure 13. VSYS Supply Current vs Temperature

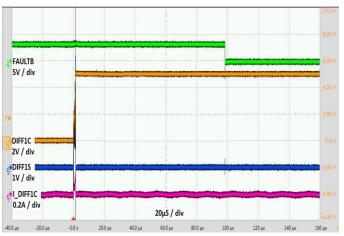


Figure 14. DIFF1C Short to 5V V<sub>BUS</sub>



## Performance Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.) (continued)



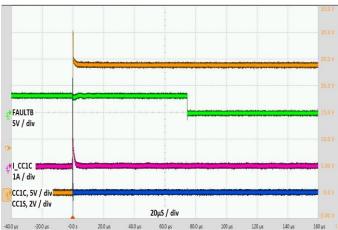
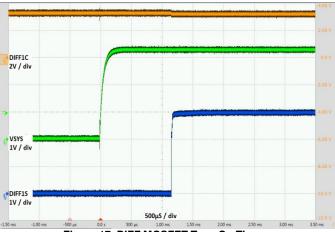


Figure 15. DIFF1C Short to 24V V<sub>BUS</sub>

Figure 16. CC1C Short to 24V VBUS



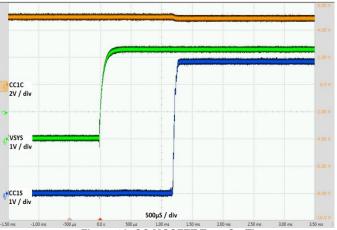
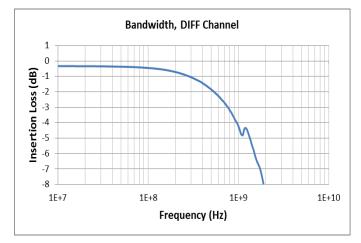


Figure 17. DIFF MOSFET Turn-On Time

Figure 18. CC MOSFET Turn-On Time



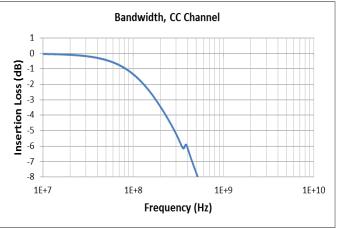


Figure 19. DIFF Channel Bandwidth

Figure 20. CC Channel Bandwidth



# Performance Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.) (continued)

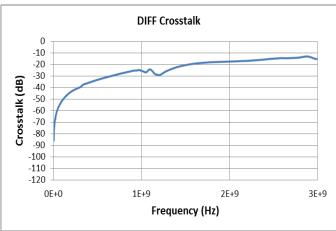


Figure 21. DIFF Crosstalk



## **Application Information**

#### **General Description**

The DPO2039 is a USB port protection device designed to work with USB Type-C connector, cable and USB PD to form a system that enables signal management and power delivery in a compact package. It provides short to VBUS protection for the CC and DIFF pins over the USB Type-C connector.

#### **Short to VBUS Protection**

The DPO2039 is a 4-channel uni-directional power switch with over-voltage protection. This is used to prevent the components inside a system which adopts the USB Type-C connector from being damaged by unexpected hazard. On the USB Type-C connector, the CC and DIFF pins are located in the close proximity of the VBUS pin. If ever the CC and/or the DIFF lines are short to the VBUS line either at the USB-C connector or at the cable end, the components (mostly ICs manufactured on the various sub-micron process nodes) behind the USB Type-C connector can easily be damaged by the resulting EOS. The damage, if occurred, is likely non-recoverable especially given that the voltage level on the VBUS line can go up to 20V or slightly higher. The DPO2039 integrates four series over-voltage FETs to protect the system side CC and DIFF lines. When either line on the Type-C connector side CC1C, CC2C, DIFF1C or DIFF2C is shorted to VBUS line, the DPO2039 will turn off the over-voltage FETs in less than 100ns window to isolate the system side CC and DIFF lines from the over-voltage connector side. When shorted to VBUS line is detected, the open-drain FAULTB will output low to indicate a fault condition.

#### Signal Operation Range

Table 1 and Table 2 show the signal operation range and output status:

0) / 4 = 1   0 / 1   0 / 1   0   1   0	0V to 5.85V	OFF
0V to UVLO (Invalid)	5.85V to 20V	OFF
	0V to 5.85V	ON
2.7V to 5.5V (Valid)	5.85V to 20V	OFF: FAULTB Asserted (OVP detected)

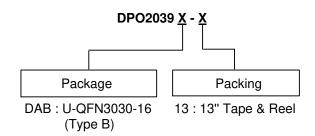
Table 1. Signal Operation Range for CCx

0) ( to 1 l) (1 0 (location)	0V to 4.35V	OFF
0V to UVLO (Invalid)	4.35V to 20V	OFF
0.7// 1- 5.5// (/-1:-1)	0V to 4.35V	ON
2.7V to 5.5V (Valid)	4.35V to 20V	OFF: FAULTB Asserted (OVP detected)

Table 2. Signal Operation Range for DIFFx



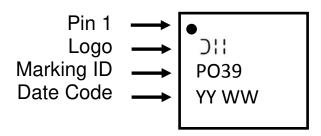
## Ordering Information (Note 7)



Part Number	Marking ID	Reel Size (inches)	Tape Width (mm)	13" Tape and Reel		
Part Number	Marking ID		rape widin (iiiii)	Quantity	Part Number Suffix	
DPO2039DAB-13	PO39	13	8	3,000/Tape & Reel	-13	

Note: 7. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



YY: Year

WW: Week 01 to 53



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

# Side View D (Pin #1 ID) E D L (16x) Z (8x)

U-QFN3030-16 (Type B)

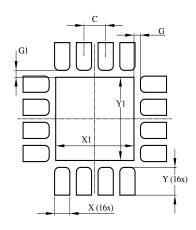
U-QFN3030-16					
Type B					
Dim	Min	Max	Тур		
Α	0.55	0.65	0.60		
A1	0	0.05	0.02		
A3	-	-	0.15		
b	0.18	0.28	0.23		
D	2.95	3.05	3.00		
D2	1.40	1.60	1.50		
Е	2.95	3.05	3.00		
E2	1.40	1.60	1.50		
е	-	-	0.50		
L	0.35	0.45	0.40		
Z	-	-	0.625		
All Dimensions in mm					

**Bottom View** 

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

## U-QFN3030-16 (Type B)



Dimensions	Value
Dillielisiolis	(in mm)
С	0.500
G	0.150
G1	0.150
X	0.350
X1	1.800
Y	0.600
Y1	1.800

## **Mechanical Data**

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu Finish, Solderable per MIL-STD-202, Method 208@4
- Weight: 0.0167 grams (Approximate)



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